## 54F08,74F08

**Quad 2-Input AND Gate** 



Literature Number: SNOS147A



December 1994

### 54F/74F08

### **Quad 2-Input AND Gate**

#### **General Description**

#### **Features**

This device contains four independent gates, each of which performs the logic AND function.

■ Guaranteed 4000V minimum ESD protection

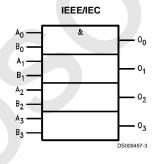
#### Ordering Code: See Section 0

Commercial	Military	Package	Package Description
		Number	
74F08PC		N14A	14-Lead (0.300" Wide) Molded Dual-In-Line
	54F08DM (Note 2)	J14A	14-Lead Ceramic Dual-In-Line
74F08SC (Note 1)		M14A	14-Lead (0.150" Wide) Molded Small Outline, JEDEC
74F08SJ (Note 1)		M14D	14-Lead (0.300" Wide) Molded Small Outline, EIAJ
	54F08FM (Note 2)	W14B	14-Lead Cerpack
	54F08LM (Note 2)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

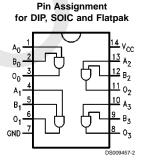
Note 1: Devices also available in 13" reel. Use suffix = SCX and SJX.

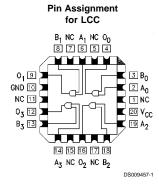
Note 2: Military grade device with environmental and burn-in processing. Use suffix = DMQB, FMQB and LMQB.

#### **Logic Symbol**



#### **Connection Diagrams**





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# Unit Loading/Fan Out See Section 0 for U.L. definitions

		54F/74F				
Pin Names	Description	U.L.	Input I <sub>IH</sub> /I <sub>IL</sub>			
		HIGH/LOW	Output I <sub>OH</sub> /I <sub>OL</sub>			
A <sub>n</sub> , B <sub>n</sub>	Inputs	1.0/1.0	20 μA/-0.6 mA			
O <sub>n</sub>	Outputs	50/33.3	–1 mA/20 mA			

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#### **Absolute Maximum Ratings** (Note 3)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Storage Temperature -65°C to +150°C

Ambient Temperature under Bias -55°C to +125°C

Junction Temperature under Bias -55°C to +175°C

Plastic -55°C to +150°C

V<sub>CC</sub> Pin Potential to

Ground Pin -0.5V to +7.0V Input Voltage (Note 4) -0.5V to +7.0V Input Current (Note 4) -30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with  $V_{CC} = 0V$ )

Standard Output -0.5V to  $V_{CC}$ TRI-STATE® Output -0.5V to +5.5V Current Applied to Output

in LOW State (Max) twice the rated  $\rm I_{OL}$  (mA) ESD Last Passing Voltage (Min) 4000V

## Recommended Operating Conditions

Free Air Ambient Temperature

Supply Voltage

Military +4.5V to +5.5V Commercial +4.5V to +5.5V

**Note 3:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 4: Either voltage limit or current limit is sufficient to protect inputs.

#### **DC Electrical Characteristics**

Symbol	Parameter		54F/74F			Units	V <sub>cc</sub>	Conditions
			Min	Тур	Max			
V <sub>IH</sub>	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal
V <sub>IL</sub>	Input LOW Voltage				8.0	V		Recognized as a LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage				-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH	54F 10% V <sub>CC</sub>	2.5					I <sub>OH</sub> = -1 mA
	Voltage	74F 10% V <sub>CC</sub>	2.5			V	Min	I <sub>OH</sub> = -1 mA
		74F 5% V <sub>CC</sub>	2.7					I <sub>OH</sub> = -1 mA
V <sub>OL</sub>	Output LOW	54F 10% V <sub>CC</sub>			0.5	V	Min	I <sub>OL</sub> = 20 mA
	Voltage	74F 10% V <sub>CC</sub>			0.5			I <sub>OL</sub> = 20 mA
I <sub>IH</sub>	Input HIGH	54F			20.0	μA	Max	V <sub>IN</sub> = 2.7V
	Current	74F			5.0			
I <sub>BVI</sub>	Input HIGH Current	54F			100	μA	Max	V <sub>IN</sub> = 7.0V
	Breakdown Test	74F			7.0			
I <sub>CEX</sub>	Output HIGH	54F			250	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
	Leakage Current	74F			50			
V <sub>ID</sub>	Input Leakage	74F	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA
	Test							All Other Pins Grounded
I <sub>OD</sub>	Output Leakage	74F			3.75	μΑ	0.0	V <sub>IOD</sub> = 150 mV
	Circuit Current							All Other Pins Grounded
I <sub>IL</sub>	Input LOW Current				-0.6	mA	Max	V <sub>IN</sub> = 0.5V
Ios	Output Short-Circuit C	urrent	-60		-150	mA	Max	V <sub>OUT</sub> = 0V
Іссн	Power Supply Current			5.5	8.3	mA	Max	V <sub>O</sub> = HIGH
I <sub>CCL</sub>	Power Supply Current			8.6	12.9	mA	Max	V <sub>O</sub> = LOW

#### **AC Electrical Characteristics**

See Section 0 for Waveforms and Load Configurations

PrintDate=1997/08/26 PrintTime=15:23:51 9460 ds009457 Rev. No. 1 cmserv

	Parameter	74F T <sub>A</sub> = +25°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50 pF			54F T <sub>A</sub> , V <sub>CC</sub> = Mil C <sub>L</sub> = 50 pF		74F T <sub>A</sub> , V <sub>CC</sub> = Com C <sub>L</sub> = 50 pF		Units	Fig. No.
0										
Symbol										
		Min	Тур	Max	Min	Max	Min	Max	-	
t <sub>PLH</sub>	Propagation Delay	3.0	4.2	5.6	2.5	7.5	3.0	6.6	ns	++-++
t <sub>PHL</sub>	$A_n$ , $B_n$ to $O_n$	2.5	4.0	5.3	2.0	7.5	2.5	6.3		

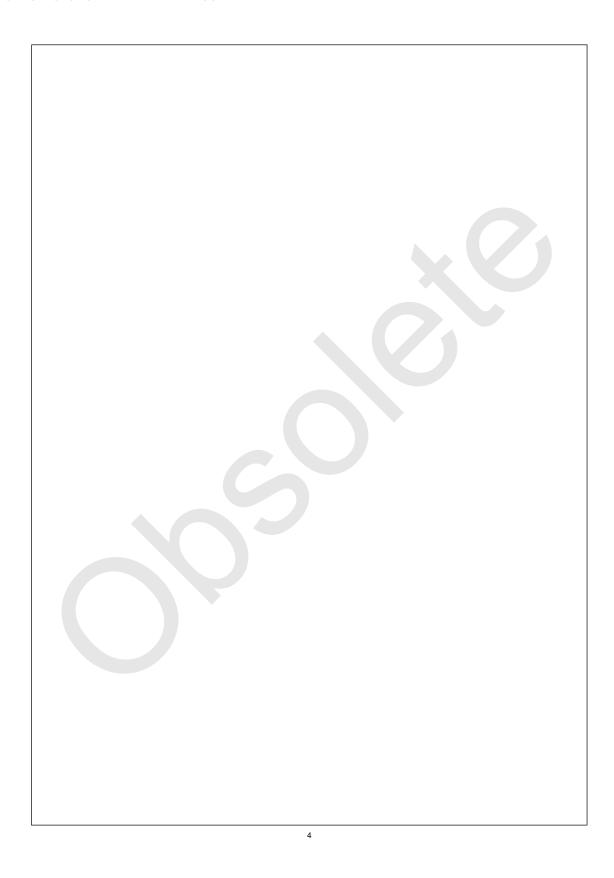
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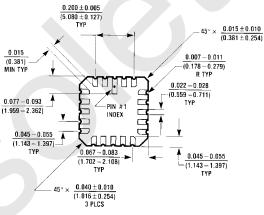
DSXXX

DSXXX



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### **Ordering Information** The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows: <u>74F</u> Temperature Range Family 74F = Commercial 54F = Military Device Type Package Code P = Plastic DIP D = Ceramic DIP F = Flatpak L = Leadless Chip Carrier (LCC) S = Small Outline SOIC JEDEC SJ = Small Outline SOIC EIAJ $\begin{picture}(200,0)\put(0,0){\line(1,0){100}} \put(0,0){\line(1,0){100}} \put(0,0){\line(1,0){100$ $\boldsymbol{0.350 \pm 0.008}$ 0.015 $\frac{0.063 - 0.075}{(1.600 - 1.905)}$ $(8.890 \pm 0.203)$ (0.381) MIN TYP 0.077 - 0.093(1.959 - 2.362)0.045 - 0.055 (1.143 - 1.397) -TYP Top View Side View



Special Variations

Temperature Range

QB = Military grade device with

 $C = Commercial (0^{\circ}C to +70^{\circ}C)$ 

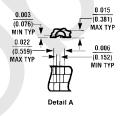
 $M = Military (-55^{\circ}C to + 125^{\circ}C)$ 

processing

environmental and burn-in

X = Devices shipped in 13" reels

**Bottom View** 



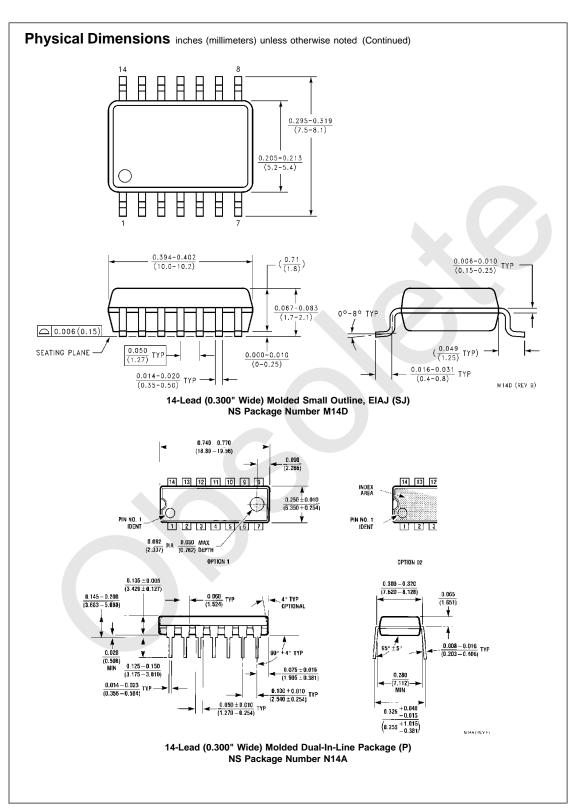
20-Lead Ceramic Leadless Chip Carrier (L) NS Package Number E20A

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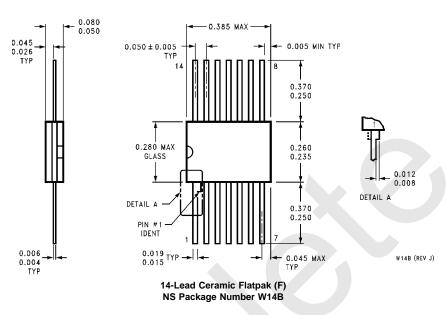
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#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



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